L Number	Hits	Search Text	DB	Time stamp
1	726	atomic adj layer adj deposit\$3	USPAT;	2003/07/09 14:10
			US-PGPUB	
2	4830	tantalum adj nitride	USPAT;	2003/07/09 14:10
		,	US-PGPUB	
3	56129	"TaN"	USPAT:	2003/07/09 14:10
			US-PGPUB	
5	68	(atomic adj layer adj deposit\$3) same ((tantalum adj nitride)	USPAT:	2003/07/09 14:51
	-	or "TaN")	US-PGPUB	

L Number	Hits	Search Text	DB	Time stamp
1	787	438/653.ccls.	USPAT;	2003/07/09 17:35
			US-PGPUB	
2	989168	tungsten or W	USPAT;	2003/07/09 17:35
			US-PGPUB	1
3	348610	copper or Cu	USPAT;	2003/07/09 17:35
			US-PGPUB	
4	261	438/653.ccls. and ((tungsten or W) same (copper or Cu))	USPAT;	2003/07/09 17:37
			US-PGPUB	
5	4830	tantalum adj nitride	USPAT;	2003/07/09 17:38
			US-PGPUB	
6	56129	"TaN"	USPAT;	2003/07/09 17:38
			US-PGPUB	
7	185580	barrier	USPAT;	2003/07/09 17:39
			US-PGPUB	
8	3335	((tantalum adj nitride) or "TaN") same barrier	USPAT;	2003/07/09 17:39
			US-PGPUB	
9	116	438/653.ccls. and ((tungsten or W) same (copper or Cu)) and	USPAT;	2003/07/09 17:39
	1	(((tantalum adi nitride) or "TaN") same barrier)	US-PGPUB	